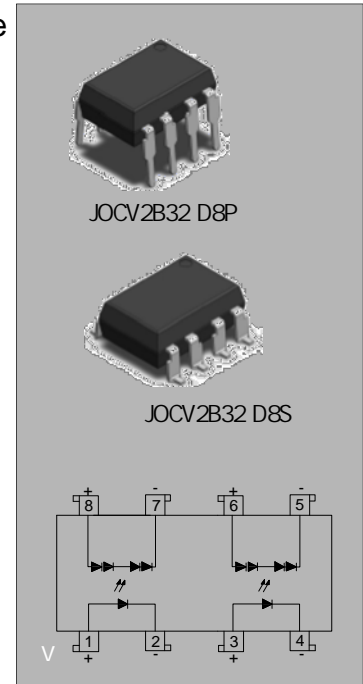




The products are voltage opto-couplers in a plastic DIP8 package with different lead forming options. The device consists of a high-voltage output detector circuit. It is capable of directly driving gates of power MOSFETs or IGBTs. The products are widely used in supply for electronic circuit and drive solid state relay.

- High isolation 5000 VRMS
- Operating temperature range -40°C to 110°C
- RoHS & REACH Compliance
- HBM: H3A; MM: M4; CDM: C3
- CQC approved
- VDE approved
- UL approved



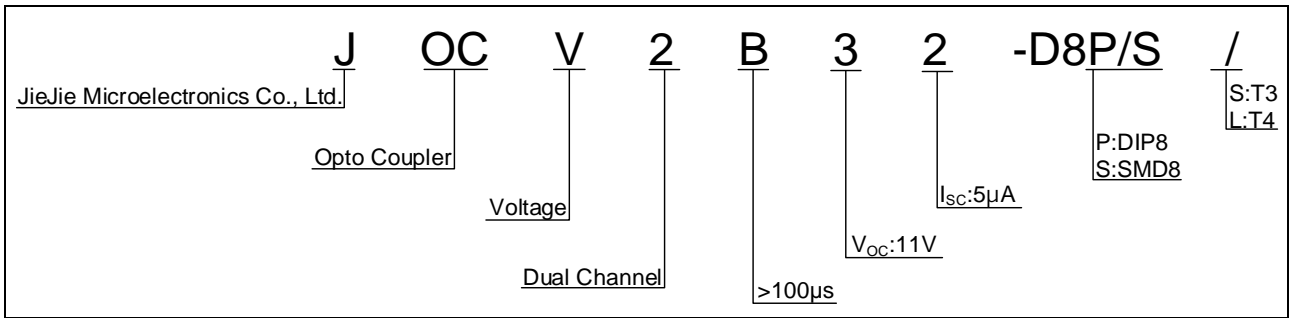
(Temperature=25°C)

| Parameter | | Symbol | Value | Unit |
|-----------------------|----------------------|-----------|----------|------|
| Input | Forward Current | I_F | 50 | mA |
| | Peak Forward Current | I_{FP} | 1 | A |
| | Reverse Voltage | V_R | 6 | V |
| | Power Dissipation | P_D | 75 | mW |
| Isolation Voltage | | V_{iso} | 5000 | Vrms |
| Operating Temperature | | T_{opr} | -40~+110 | |
| Junction Temperature | | T_j | 125 | |
| Storage Temperature | | T_{stg} | -55~+125 | |
| Soldering Temperature | | T_{sol} | 260 | |

: 100μs pulse, 100Hz frequency
 : AC for 1minute, R.H.=40~60%

(Temperature=25°C)

| Parameter | | Symbol | Condition | Min. | Typ. | Max. | Unit |
|--------------------------|-----------------------|-----------|---------------------------------------|-----------|------|------|---------------|
| Input | Forward Voltage | V_F | $I_F=10\text{mA}$ | - | 1.2 | 1.5 | V |
| | Reverse Current | I_R | $V_R=6\text{V}$ | - | - | 1 | μA |
| Output | Open Circuit Voltage | V_{OC} | $I_F=10\text{mA}$ $I_O=0\text{mA}$ | 11 | - | - | V |
| | Short Circuit Current | I_{SC} | $I_F=10\text{mA}$ $V_O=0\text{V}$ | 5 | - | - | μA |
| Transfer Characteristics | Isolation resistance | R_{IO} | DC500V 40~60%R.H. | 10^{12} | - | - | |
| | Response Time | t_{on} | $I_F=10\text{mA}$ | - | 100 | - | μs |
| | | t_{off} | | - | 50 | - | μs |



| | | | |
|-----|-----------------|--------------------|----------------------------------|
| | | | |
| DIP | 50 Units/Tube | 40 Tubes/Inner box | 5 Inner box/Outer box =10k Units |
| SMD | 1200 Units/Reel | 2 Reels/Inner box | 5 Inner box/Outer box =12k Units |

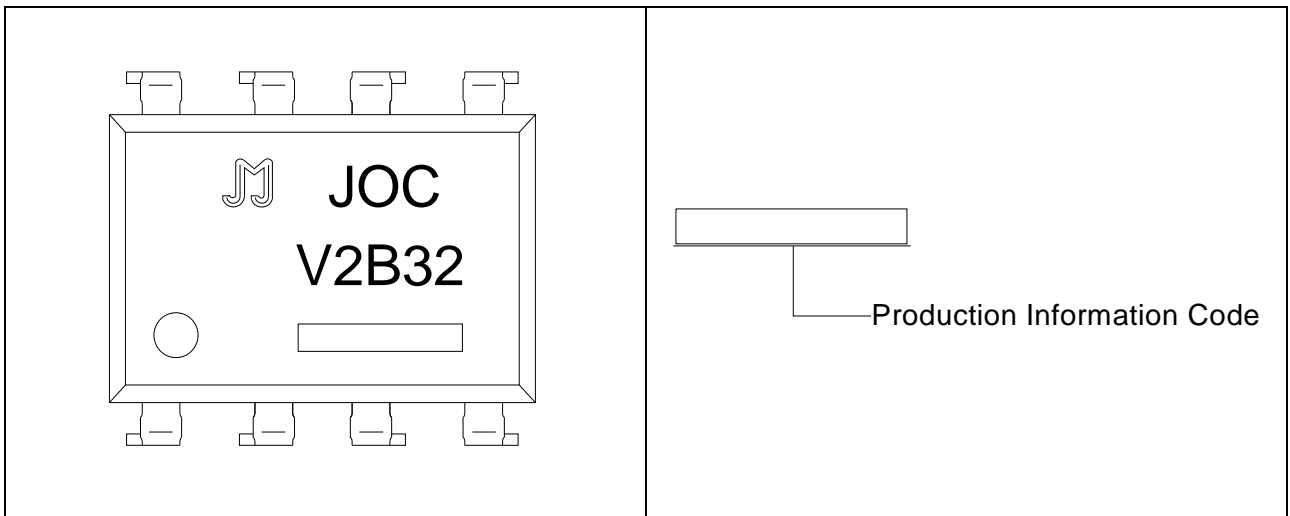


FIG.1: Max. Allowable LED Forward Current vs. Ambient Temperature

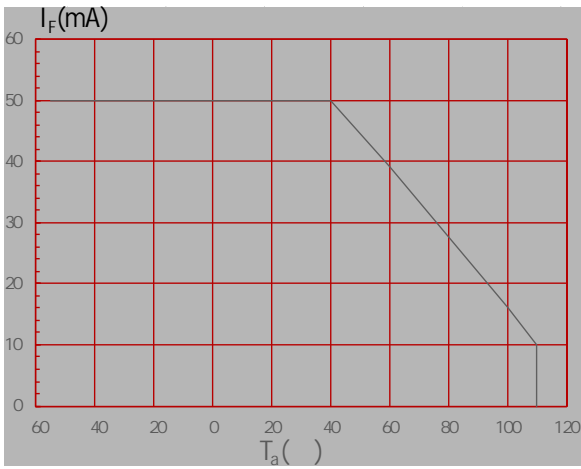


FIG.2: Forward Current vs. Forward Voltage

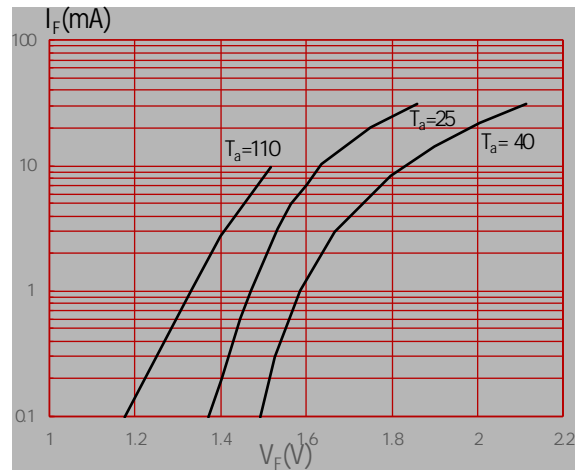


FIG.3: Open Circuit Voltage vs. Forward Current

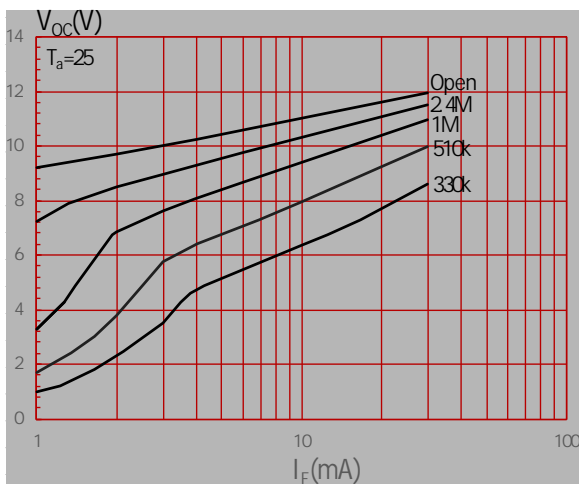


FIG.4: Short Circuit Current vs. Forward Current

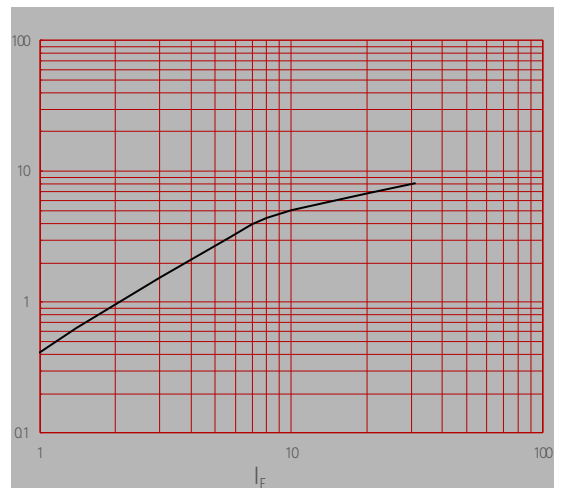
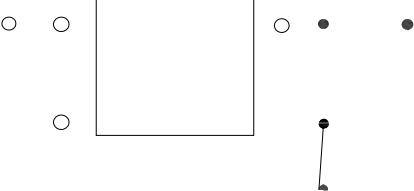
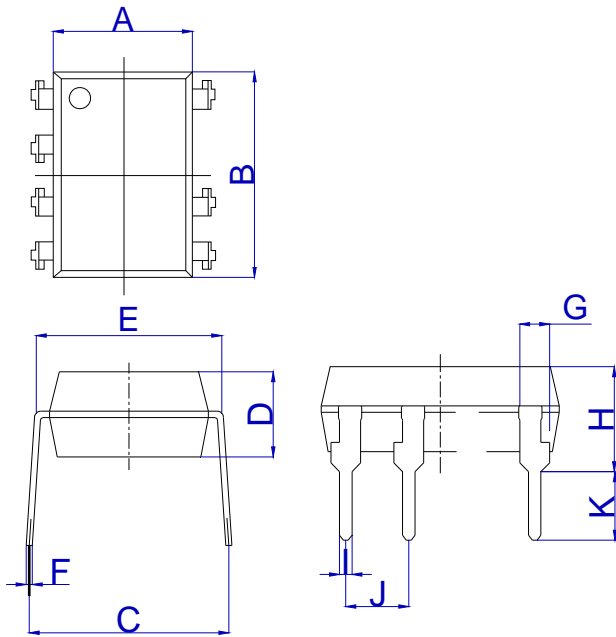


FIG.7: Response Time Test Circuit, Waveform

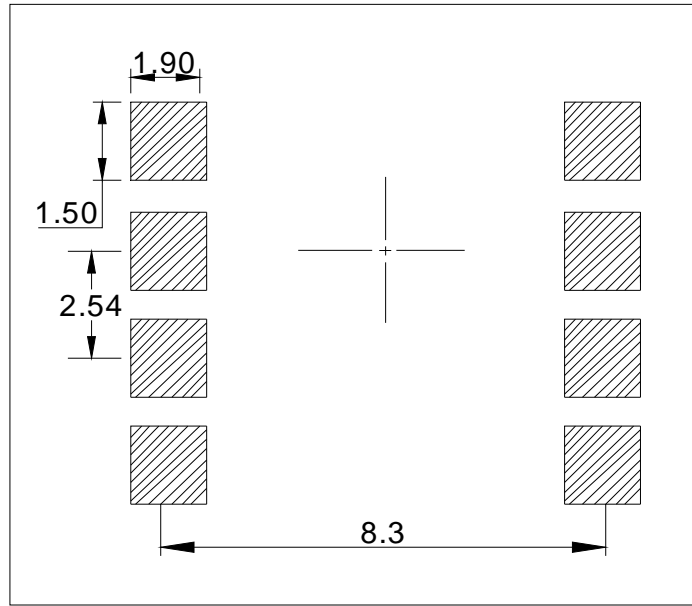


Standard DIP Type:

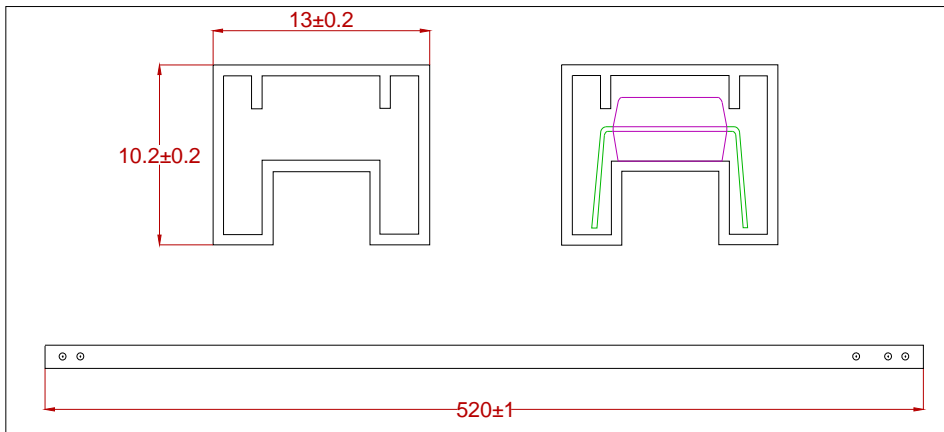


| Ref. | Dimensions | | | | | |
|------|-------------|------|------|--------|------|-------|
| | Millimeters | | | Inches | | |
| | Min. | Typ. | Max. | Min. | Typ. | Max. |
| A | 6.20 | | 6.60 | 0.244 | | 0.260 |
| B | 9.40 | | 9.80 | 0.370 | | 0.386 |
| C | 7.15 | | 8.95 | 0.281 | | 0.352 |
| D | 3.20 | | 3.60 | 0.126 | | 0.142 |
| E | 7.32 | | 7.92 | 0.288 | | 0.312 |
| F | 0.15 | | 0.35 | 0.006 | | 0.014 |
| G | 0.90 | | 1.50 | 0.035 | | 0.059 |
| H | 3.90 | | 4.50 | 0.154 | | 0.177 |
| I | 0.40 | | 0.60 | 0.016 | | 0.024 |
| J | 2.29 | | 2.79 | 0.090 | | 0.110 |
| K | 2.24 | | 3.24 | | | |

9 i

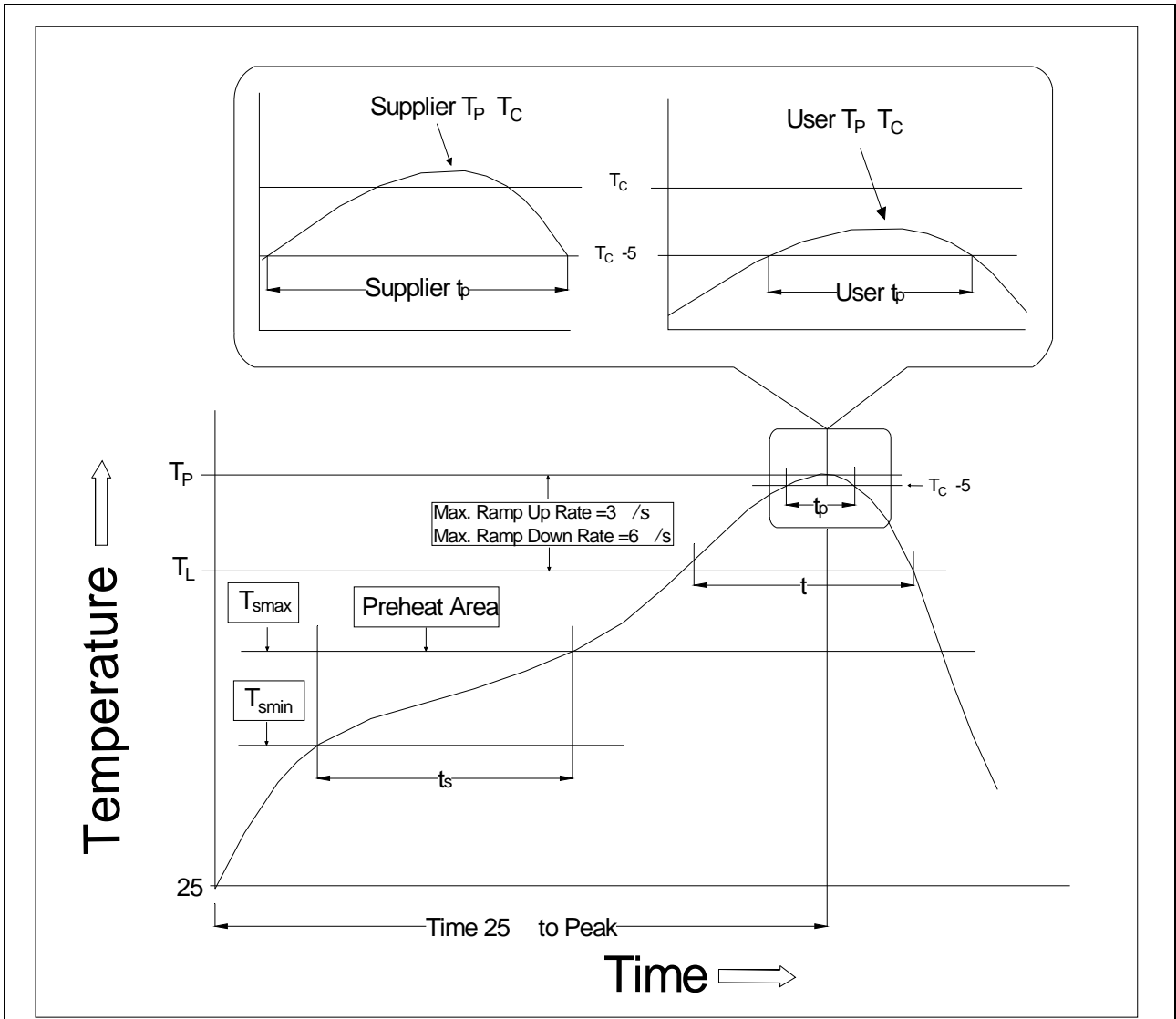


Standard DIP

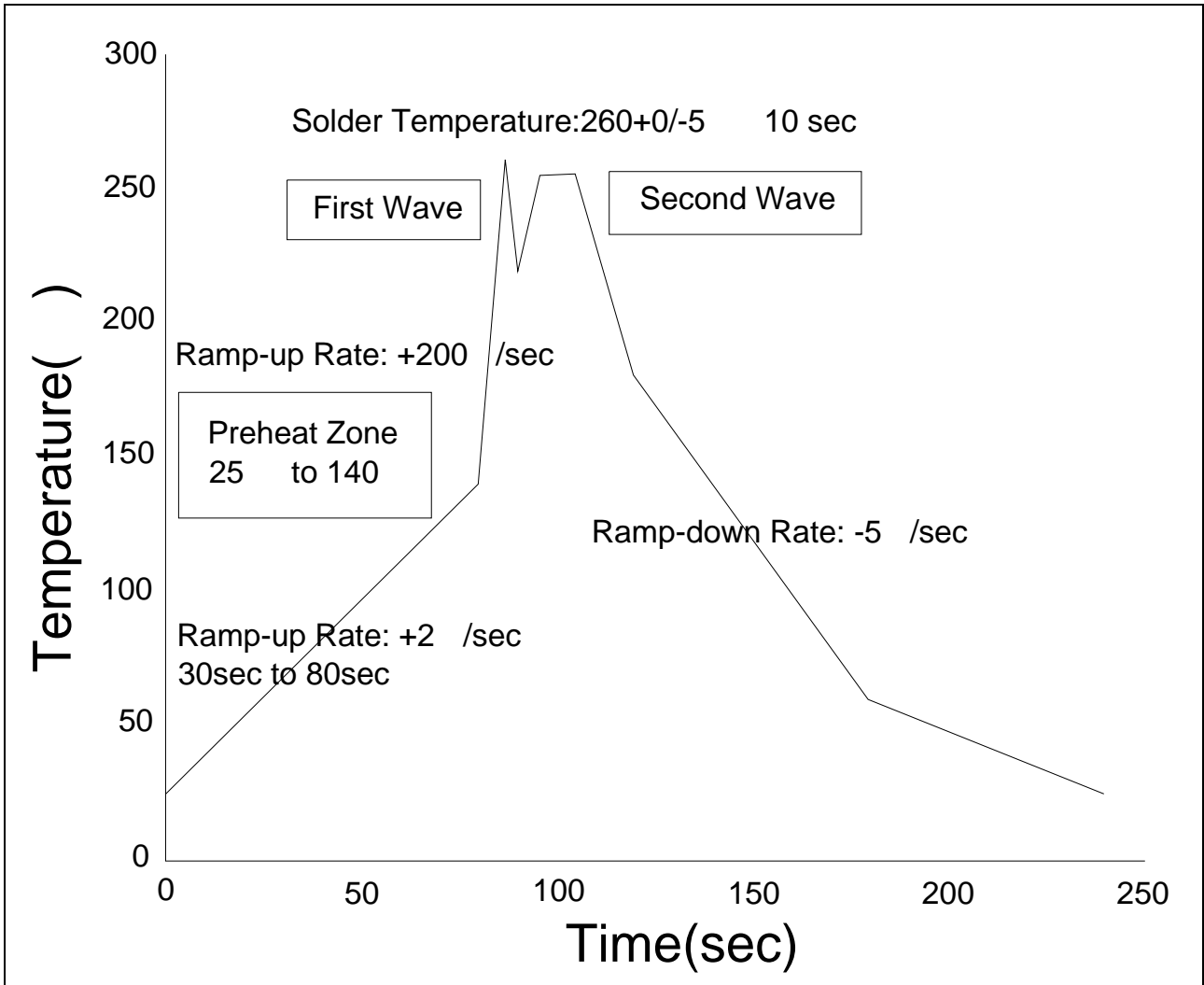


Option S

| Ref. | Dimensions | | | Inches |
|------|-------------|------|------|--------|
| | Millimeters | | | |
| | Min. | Typ. | Max. | Min. |



| Profile Feature | Sn-Pb Assembly Profile | Pb-Free Assembly Profile |
|---|------------------------|--------------------------|
| Temperature Min. (T _{smin}) | 100 | 150 |
| Temperature Max. (T _{smax}) | 150 | 200 |
| Time (t _s) from (T _{smin} to T _{smax}) | 60-120 seconds | 60-120 seconds |
| Ramp-up Rate (t _L to t _P) | 3 °/second max. | 3 °/second max. |
| Liquidus Temperature (T _L) | 183 | 217 |
| Time (t _L) Maintained Above (T _L) | 60-150 seconds | 60-150 seconds |
| Peak Body Package Temperature | 235 +0 /-5 | 260 +0 /-5 |
| Time (t _P) within 5 ° of 260 | 10 seconds | 10 seconds |
| Ramp-down Rate (T _P to T _L) | 3-6 °/second | 3-6 °/second |
| Time 25 ° to Peak Temperature | 6 minutes max. | 8 minutes max. |



| | |
|-----------------------|---------|
| | |
| Soldering Temperature | 360± 5 |
| Soldering Time | 3s max. |

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.
2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.
3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.
4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.
5. The component has a shelf life of one year when stored under standard conditions.
6. Recommend storage Temp.: 0~40°C;
Recommend storage humidity: <60%;
MSL level: MSL 1

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